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APPLICATION NO	HUNG DATE	FIRST NAMEDINVENTOR	ATTORNEY DOCKET NO	CONFIRMATION NO	
09 993,223	11 26 2001	Kenichi Kurisu	50395-125	6863	
75	90 07 16 2003				
McDERMOTT, WILL & EMERY			EXAMINER		
600 13th Street, N.W. Washington, DC 20005-3096			VINH,	VINH, LAN	
			ART UNIT	PAPER NUMBER	
			1765	$\overline{}$	
			DATE MAILED: 07/16/2003	/	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
		09/993,223	KURISU, KENICHI
•	Office Action Summary	Examiner	Art Unit
		Lan Vinh	1765
Period fo	The MAILING DATE of this communication a or Reply	ppears on the cover sheet v	vith the correspondence address
THE - External after - If the - If NC - Failu - Any r	ORTENED STATUTORY PERIOD FOR REP MAILING DATE OF THIS COMMUNICATION asions of time may be available under the provisions of 37 CFR 1 SIX (6) MONTHS from the mailing date of this communication, period for reply specified above is less than thirty (30) days, a reperiod for reply is specified above, the maximum statutory perion reply within the set or extended period for reply will, by statutely received by the Office later than three months after the mailed patent term adjustment. See 37 CFR 1.704(b).	I. 1. 136(a) In no event, however, may a eply within the statutory minimum of th d will apply and will expire SIX (6) MC ute, cause the application to become A	reply be timely filed irty (30) days will be considered timely NTHS from the mailing date of this communication. ABANDONED (35 U.S.C. § 133).
1)	Responsive to communication(s) filed on <u>07</u>	⁷ May 2003 .	
2a) <u></u> □	This action is FINAL . 2b) 2	This action is non-final.	
3) <u> </u>	Since this application is in condition for allow closed in accordance with the practice unde on of Claims		
4)	Claim(s) 1-12 is/are pending in the application	on.	
	4a) Of the above claim(s) is/are withdr	awn from consideration.	
5)[Claim(s) is/are allowed.		
6)[Claim(s) <u>1-12</u> is/are rejected.		
7)	Claim(s) is/are objected to.		
8)	Claim(s) are subject to restriction and	or election requirement.	
Applicati	on Papers		
9) 🗌 .	The specification is objected to by the Examir	ner.	
10) 🗌 🤄	The drawing(s) filed on is/are: a)□ acc	epted or b) objected to by	the Examiner.
	Applicant may not request that any objection to t	the drawing(s) be held in abe	vance. See 37 CFR 1.85(a).
11)[_]	The proposed drawing correction filed on		disapproved by the Examiner.
	If approved, corrected drawings are required in r	, ,	
	The oath or declaration is objected to by the E	Examiner.	
	ınder 35 U.S.C. §§ 119 and 120		
	Acknowledgment is made of a claim for foreign	gn priority under 35 U.S.C.	§ 119(a)-(d) or (f).
a)[☑ All b)☐ Some * c)☐ None of:		
	1 Certified copies of the priority documer		
	2. Certified copies of the priority documer		
* S	3 Copies of the certified copies of the pri application from the International E ee the attached detailed Office action for a lis	Bureau (PCT Rule 17.2(a)).	-
14) 🗌 A	cknowledgment is made of a claim for domes	stic priority under 35 U.S.C	. § 119(e) (to a provisional application).
a	The translation of the foreign language packnowledgment is made of a claim for domes	rovisional application has t	peen received.
Attachment	(s)		
2) 🔲 Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disciosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of	Summary (PTO-413) Paper No(s) Informal Patent Application (PTO-152)
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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1, 4 are rejected under 35 U.S.C. 103(a) as being unpatentable over Narui et al (US 5,475,237) in view of Biricik et al (US 5,173,443)

Narui discloses a method for forming a light emitting device/optical element having a layer that makes diffraction grating (col 2, lines 31-34). This method comprises the step of etching a pattern in a ZnSe layer 10 by RIE method using a gas of boron trichloride (BCl₃) (col 5, lines 55-56; col 6, lines 26-28), which reads on RIE a pattern in a ZnSe substrate by means of only chlorine-based gas which does not include a hydrocarbon group.

Unlike the instant claimed invention as per claim 1, Narui does not disclose that the ZnSe substrate is a polycrystalline substrate

However, Biricik, in a method of manufacturing optical semiconductor windows, teaches forming a polycrystalline ZnSe substrate (col 15, lines 33-34)

Since Narui is concerned with a method of forming an optical element, one skilled in the art would have found it obvious to modify Narui method by forming a polycrystalline ZnSe substrate as per Biricik because Biricik teaches that polycrystalline ZnSe are preferred substrates for optical transmission (col 15, lines 32-34)

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The limitation of claim 4 has been discussed above.

3. Claims 2, 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Narui et al (US 5,475,237) in view of Biricik et al (US 5,173,443)

Narui discloses a method for forming a light emitting device/optical element having a layer that makes diffraction grating (col 2, lines 31-34). This method comprises the step of etching a pattern in a ZnSe layer 10 by RIE method using a mixed gas of boron trichloride (BCl₃) and He/helium/inert gas (col 5, lines 55-56; col 6, lines 26-28), which reads on RIE a pattern in a ZnSe substrate with a mixture of a chlorine-based gas which does not include a hydrocarbon group and inert gas

Unlike the instant claimed invention as per claim 2, Narui does not disclose that the ZnSe substrate is a polycrystalline substrate

However, Biricik, in a method of manufacturing optical semiconductor windows, teaches forming a polycrystalline ZnSe substrate (col 15, lines 33-34)

Since Narui is concerned with a method of forming an optical element, one skilled in the art would have found it obvious to modify Narui method by forming a polycrystalline ZnSe substrate as per Biricik because Biricik teaches that polycrystalline ZnSe are preferred substrates for optical transmission (col 15, lines 32-34)

The limitation of claim 7 has been discussed above

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4. Claims 3, 8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Narui et al (US 5,475,237) in view of Biricik et al (US 5,173,443) and further in view of Collins (US 5,707,486)

Narui as modified by Biricik has been described above in paragraph 3. Narui and Biricik differ from the instant claimed invention as per claim 3 by using an inert gas of helium instead of argon.

However, Collins, in a process of plasma etching/RIE etching, teaches that an inert gas such as argon and helium can be added to the etching gas chemistry (col 18, lines 9-11)

Since Narui is concerned with a step of RIE etching, one skilled in the art would have found it obvious to substitute Narui and Biricik inert gas of helium with argon in view of Collins's teaching because both gases are known inert gases and Collins states that argon is the preferred inert gas additive, because it is relatively massive and thus contributes to the sputter etch component of the RIE process (col 17, lines 32-35)

The limitation of claim 8 has been discussed above.

5. Claims 5, 9, 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Narui et al (US 5,475,237) in view of Biricik et al (US 5,173,443) and further in view of Harafuji (US 5,635,021)

Narui as modified by Biricik has been described above in paragraph 3. Unlike the instant claimed invention as per claims 5, 9, 10, Narui and Biricik do not specifically disclose performing the RIE etching at a gas pressure of 0.5 Pa through 1 Pa.

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However, Harafuji, in a method of dry etching using RIE, teaches setting the gas pressure of a chlorine-based gas such as BCl₃ at a pressure of 0.1-20 Pa (overlaps the claimed range of 0.5-1 Pa) during RIE etching (col 38, lines 55-61)

Since both Narui and Harafuji are concerned with RIE etching step using chlorine-based gas, one skilled in the art would have found it obvious perform Narui and Biricik's RIE etching step at a pressure range as taught by Harafuji especially since Harafuji states that when other plasma internal parameters than the gas pressure are constant, the spread of the ion angular distribution can be controlled to a certain degree by changing the gas pressure of about 1 Pa (col 20, lines 64-67)

6. Claims 6, 11, 12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Narui et al (US 5,475,237) in view of Biricik et al (US 5,173,443) and further in view of Kim et al (US 6,037,267)

Narui as modified by Biricik has been described above in paragraph 3. Unlike the instant claimed invention as per claims 6, 11, 12, Narui and Biricik do not specifically disclose activating the gas by means of radio frequency (RF)

However, Kim discloses a method of etching using RIE etching comprises the step of supplying RF (radio frequency) coil power to the upper electrode to excite the species of the gas (col 4, lines 38-41), which reads on activating the gas by means of radio frequency (RF)

Since Narui is concerned with RIE etching step, one skilled in the art would have found it obvious to modify Narui and Biricik RIE etching step by activating the gas by

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means of radio frequency (RF) as per Kim because according to Kim the coil RF power also constrains the electron to orbit in a plasma region away form the chuck, the electrons of the plasma then interact with other species of the etching gas to form ions and radicals (col 4, lines 42-45)

Response to Arguments

Applicant's arguments with respect to claims 1-6 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lan Vinh whose telephone number is 703 305-6302. The examiner can normally be reached on M-F 8:30-5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Benjamin Utech can be reached on 703 308-3836. The fax phone numbers for the organization where this application or proceeding is assigned are 703 872-9310 for regular communications and 703 872-9311 for After Final communications.

July 10, 2003